PCN Number:		20180731001				P	PCN Date: Aug 7 2018			
Title: Qualification			of a new material set for select devices in the SOP package							
Customer Contact:		er Contact:	PCN N	<u>lanager</u>	Dept:	Quality Service		es		
Proposed 1 st Ship Da			te: Nov 7 2018			Estimated Samp Availability:		e Provided Request		on
Change Type:										
		embly Site		Assembly Process Assembl			Assembly Ma	aterials		
			Electrical	Electrical Specification			Mechanical Specification			
			Packing/S	Packing/Shipping/Labeling			Test Process			
	Wafe	er Bump Site		Wafer Bu	ımp Matei	rial		Wafer Bump Process		
	Wafe	er Fab Site		Wafer Fa	Wafer Fab Materials			Wafer Fab Process		
				Part num	ber chan	ge				
					PCN D	etails				
Des	script	ion of Chang	e:							
							ne	w material set	for the devices	S
liste	ed in t	the product aff	ected	section belo	ow as foll	ows:				
					Curr	ent		Additional		
Мо		unt Compour	nd		4042500			4147858		
		ld Compound		4	042503/n	on green		4211880	/green	
Bond wire		nd wire			Au/0.96 mils			Au/0.96 mils or		
composition/di			er				Cu/0.96 mils			
Moist Level/ECA		AT_		Level1-220C			Level1-260CG			
Reason for Change:										
Continuity of Supply										
Ant	ticipa	ted impact o	n Fit,	Form, Fun	ction, Qu	uality or Reli	iabi	ility (positive	/ negative):	
Nor	ne									
Anticipated impact on Material Declaration										
	No Impact to the Material Declarations or Product Content reports are driven			are driven from	n					
	Material Declaration production data and will be available following the production									
release. Upon production releas			se the revised reports can be							
				obtained	obtained from the <u>TI ECO website</u> .					
Changes to product identification resulting from this PCN:										
Not Applicable										
Product Affected										

Product Affected								
SN65ALS541NS	SN65ALS541NSRG4	SN65ALS544NS	SN65ALS544NSRG4					
SN65ALS541NSR	SN65ALS543NSR	SN65ALS544NSR						



Qualification Report

Mold compound and Die attach change and Cu for SN65ALS541/543/544NS Approve Date 25-Jul-2018

Product Attributes

Attributes	Qual Device: SN65ALS543NSR	QBS Package Reference: <u>1P8T245NSR</u>	QBS Package Reference: <u>2F1177NS</u>	QBS Package Reference: <u>SN75ALS192PW</u>
Assembly Site	MLA	MLA	MLA	MLA
Package Family	SOP	SOP	SOP	TSSOP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	SFAB	FFAB	SFAB	SFAB
Wafer Fab Process	HYB_OI	ASL3C	Ol2	Ol2

⁻ QBS: Qual By Similarity

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: SN65ALS543NSR	QBS Package Reference: <u>1P8T245NSR</u>	QBS Package Reference: <u>2F1177NS</u>	QBS Package Reference: <u>SN75ALS192PW</u>
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
WBP	Bond Pull	Wires	3/228/0	3/228/0	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0	3/228/0	3/228/0

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

⁻ Qual Device SN65ALS543NSR is qualified at LEVEL1-260C

 $⁻ The following are equivalent \ HTOL\ options\ based\ on\ activation\ energy\ of\ 0.7eV:\ 125C/1k\ Hours,\ 140C/480\ Hours,\ 150C/300\ Hours,\ and\ 155C/240\ Hours,\ 150C/300\ Hours,\ 150C/$

 $⁻ The following are equivalent \ HTSL \ options \ based \ on \ activation \ energy \ of \ 0.7eV: 150C/1k \ Hours, and \ 170C/420 \ Hours$

⁻ The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/